

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 07170077

PUBLICATION DATE : 04-07-95

APPLICATION DATE : 16-12-93

APPLICATION NUMBER : 05316700

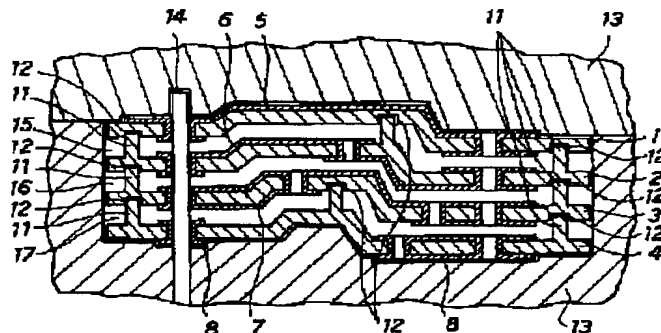
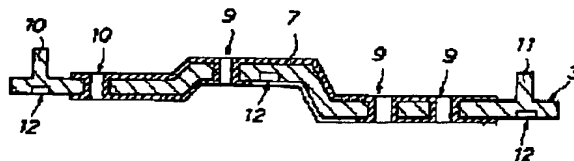
APPLICANT : HITACHI CABLE LTD;

INVENTOR : SATO AKIRA;

INT.CL. : H05K 3/46 B29C 45/14 H05K 1/14

H05K 3/00

TITLE : MANUFACTURE OF
INJECTION-MOLDED CIRCUIT PART



ABSTRACT : **PURPOSE:** To enhance a circuit part in wiring density by a method wherein a positioning hole provided with a part of a conductor circuit on its inner surface is so provided to each of injection-molded circuit members possessed of conductor circuits as to be arranged in a line when the circuit members are laminated, a spacing projection and a projection receiving recess are provided to the circuit member, and the circuit members are laminated to constitute multilayered conductor circuits.

CONSTITUTION: Positioning holes 10 provided with parts of conductor circuits 5, 6, 7, and 8 on their inner surfaces are so provided to injection-molded circuit members 1, 2, 3, and 4 possessed of conductor circuits 5, 6, 7, and 8 as to be arranged in a line when the circuit members 1, 2, 3, and 4 are laminated. Furthermore, spacing projections 11 and/or projection receiving recesses 12 are provided to the circuit member 1, 2, 3, and 4 respectively so as to provide a prescribed gap between the injection-molded circuit members 1, 2, 3, and 4 respectively. The circuit member 1, 2, 3, and 4 are laminated together making the spacing projections 11 be fitted into the recesses 12 and set in a molding die 13, and the positioning holes 10 are fixed by a positioning pin 14 provided inside the molding die 13. After the setting is finished, gaps 15, 16, and 17 provided between the circuits 1 to 4 are filled with resin by injection. Thus the conductor circuit 5 to 8 provided to both the sides of the circuit members 1 to 4 are electrically connected.

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